

## General Description

The MY80N02NE3 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

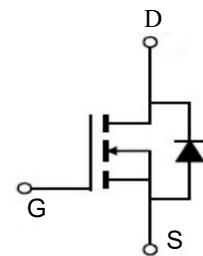
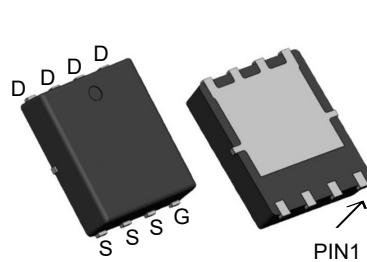


## Features

V <sub>DSS</sub>	20	V
I <sub>D</sub>	80	A
R <sub>DS(ON)</sub> (at V <sub>GS</sub> = 10V)	3.1	mΩ
R <sub>DS(ON)</sub> (at V <sub>GS</sub> = 4.5V)	4.2	mΩ

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY80N02NE3	PDFN3*3-8	MY80N02NE3	5000

## Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	20	V
V <sub>GS</sub>	Gate- Source Voltage	±12	V
I <sub>D</sub> @ T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	80	A
I <sub>D</sub> @ T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	42	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	210	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	200	mJ
P <sub>D</sub> @ T <sub>c</sub> =25°C	Total Power Dissipation <sup>4</sup>	60	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	C
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	2.1	C/W

**Electrical Characteristics (T<sub>j</sub>=25 °C, unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	22	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =19.5V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	0.4	0.7	1.1	V
Drain-Source On-State Resistance	R <sub>D(S)ON</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20 A	-	3.1	5	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =20A		4.2	9	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	15	-	-	S
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1.0MHz	-	2000	-	PF
Output Capacitance	C <sub>oss</sub>		-	500	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	200	-	PF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =10V, I <sub>D</sub> =2A, R <sub>L</sub> =1Ω V <sub>GS</sub> =4.5V, R <sub>G</sub> =3Ω	-	6.4	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	17.2	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	29.6	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	16.8	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	27	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	6.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	6.4	-	nC
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	-		1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	60	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, IF = 20A di/dt = 100A/μs <sup>(Note 3)</sup>	-	25	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	24	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition : T<sub>j</sub>=25°C, V<sub>DD</sub>=10V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω,

### Typical Characteristics

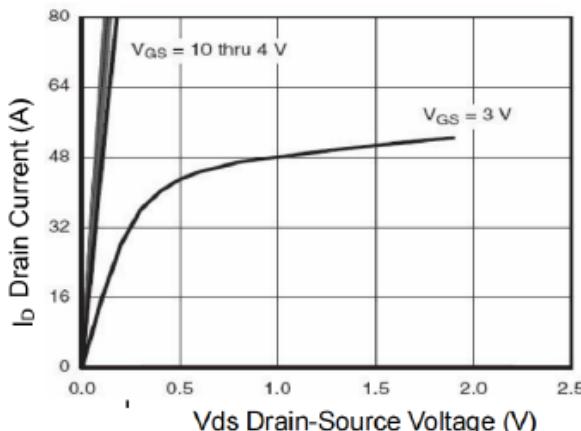


Figure 1 Output Characteristics

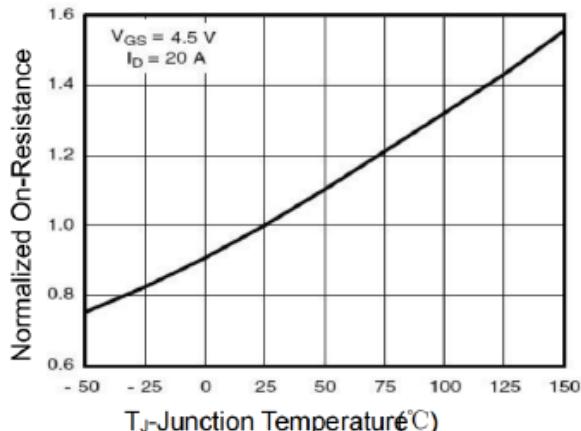


Figure 4  $R_{DS(on)}$ -Junction Temperature

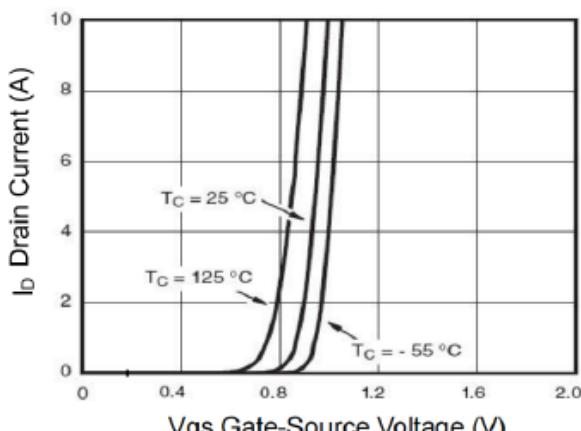


Figure 2 Transfer Characteristics

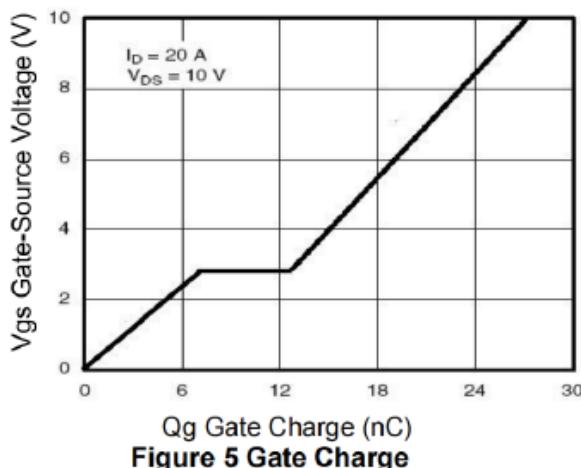


Figure 5 Gate Charge

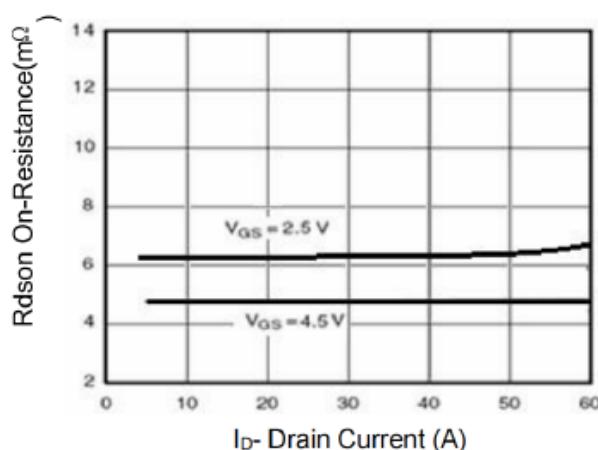


Figure 3  $R_{DS(on)}$ - Drain Current

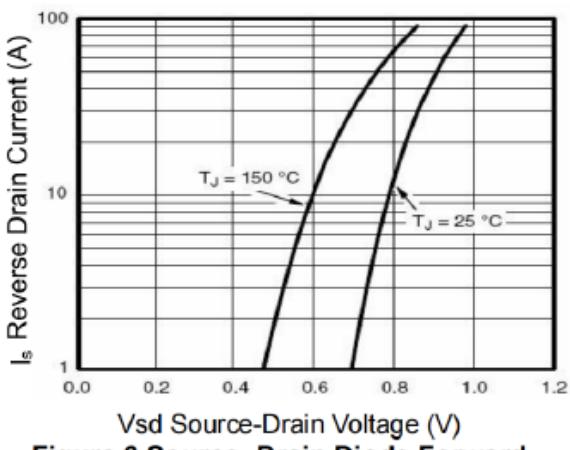


Figure 6 Source-Drain Diode Forward

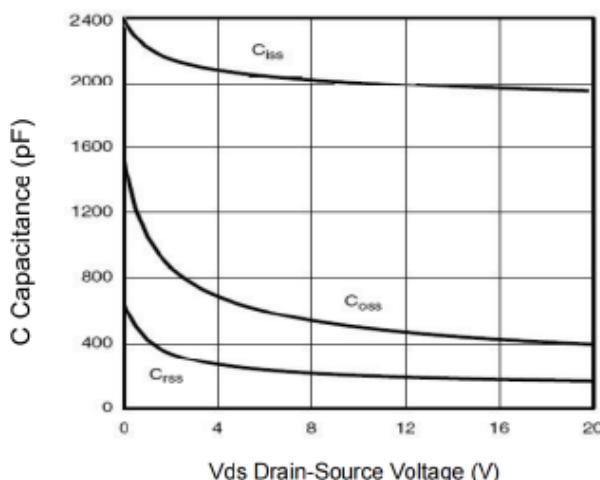


Figure 7 Capacitance vs Vds

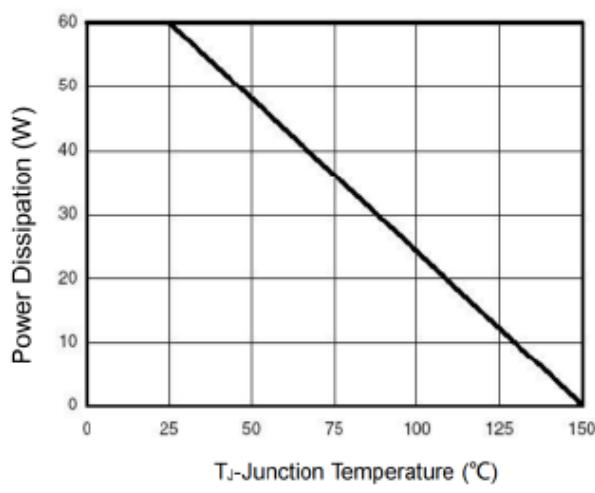


Figure 9 Power De-rating

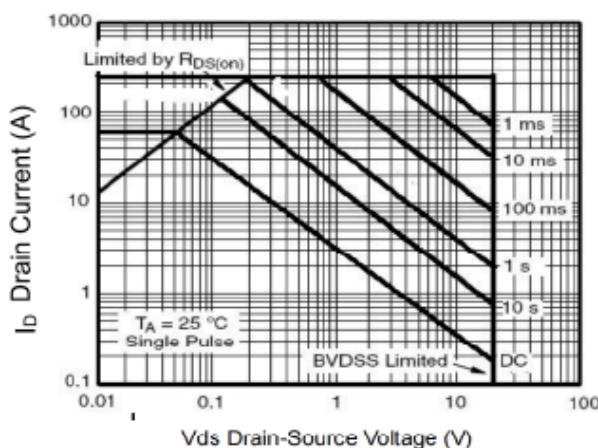


Figure 8 Safe Operation Area

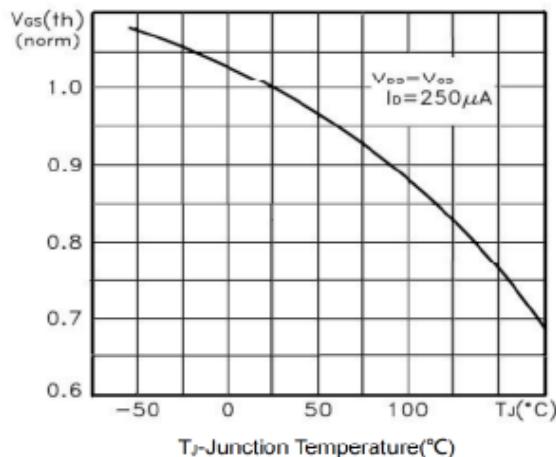
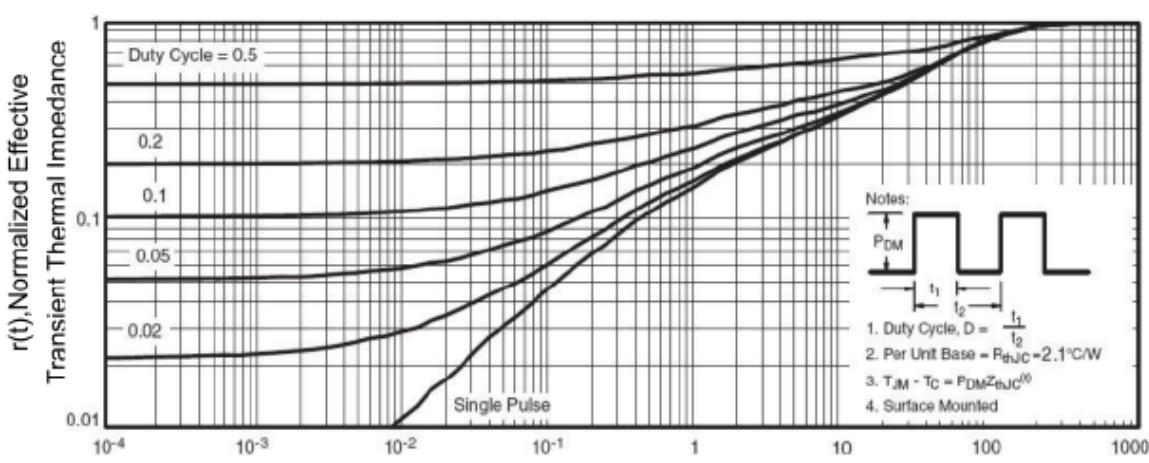
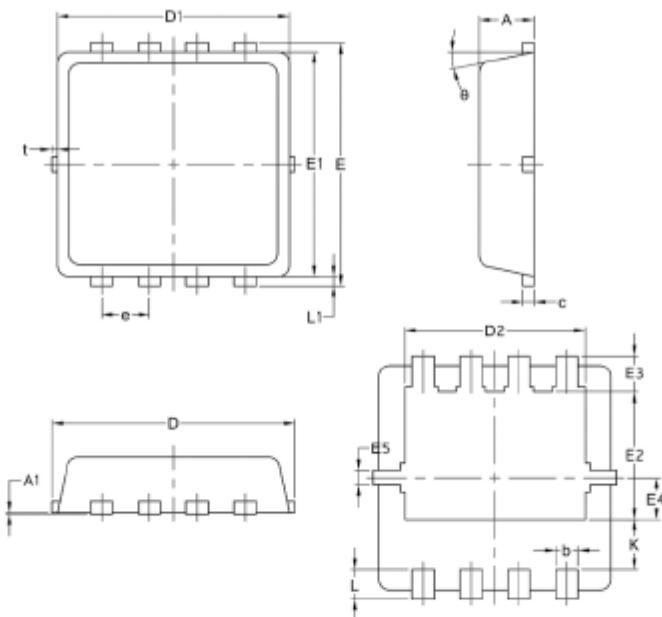
Figure 10  $V_{gs(\text{th})}$  vs Junction Temperature

Figure 11 Normalized Maximum Transient Thermal Impedance

**Package Mechanical Data PDFN3\*3-8**


Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14